AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0014] as follows:

The base 106 further includes a sound inlet port 126 positioned distal to the top edge 110. A sound inlet tube 128 that includes a mounting plate 130 and a sound passage 132 can be positioned adjacent to the sound inlet port 126 to direct the received acoustic waves into the base 106. The mounting plate 130 secures the sound inlet tube 128 to the base 106. The mounting plate 130 can be fixedly attached using, for example, a glue or epoxy, or removably attached using any know fastener. The sound passage 132 can be formed through the sound inlet tube 128 in any suitable manner such as drilling, punching or molding. A damping element or filter [[134]] 135 (see FIG. 4) positioned within the sound passage 132 provides an acoustical [[reisstance]] resistance to the microphone assembly 100. In [[orderation]] operation, sonic energy or acoustic waves enter the microphone assembly 100 via the sound passage 132. Thereafter, the sonic energy or acoustic waves communicates to the sound inlet port 126. The sound inlet tube 128, as discussed above in connection with the housing 102, can be manufactured from a variety of materials such as, for example, stainless steel, alternating layers of conductive materials, alternating layers of non-conductive materials (e.g., metal particle-coated plastics).

Please amend paragraph [0022] as follows:

To further reduce the sensitivity to low and high radio frequency interference signals, the preamplifier assembly 122 connects to the base 106 via the mounting frame 108 by means of the conductive adhesive 152, 154 to ground the RFI signals caused by communications device. The cover 104 is, in turn, grounded to the preamplifier assembly 122 by the wire [[bonding 150]] bond 156. Thus, the RFI present with the amplifier output signal supplied by the output connection 160 is suppressed.

Please amend paragraph [0023] as follows:

The preamplifier assembly 122 can be a capacitively coupled circuit including the FET [[134]] 150 adapted to reduce the RFI generated by communications devices. The circuit can further include an electrical ground path between the ground connection 162 and

the cover 104 via the wire bond 156. The electrical ground path formed between the cover 104 and the ground connection 162 effectively short-circuits undesirable RFI generated by any nearby communication devices. The wire bond 156 fixedly connects to the opening 114 of the cover 104 using a conductive adhesive such as an epoxy with suspended metallic flakes. In particular, the conductive adhesive can be a two-part silver epoxy adhesive that provides high electrical conductivity and strong conductive bonding. Conductive adhesive can replace traditional tin lead (Sn-Pb) solder and can further act as an effective heat sink.

Please amend paragraph [0024] as follows:

The preamplifier assembly 122 can further include a first resistance-capacitance network and a second resistance-capacitance network (not shown) communicatively connected to the FET 150. The first resistance-capacitance network connects to the ground point 148 by means of conductive adhesive 152 to suppress the undesirable RFI generated by nearby communication devices. The second resistance-capacitance network connects to the base 106 via the mounting frame 108 by means of conductive adhesive 154 to suppress the undesirable RFI generated by nearby communication devices.